

Notification Number:	20151007000	Notification Date:	11/9/2015
Title:	Datasheet update for TPS51200-Q1		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is updated as seen in the change revision history below:



TPS51200-Q1

SLUS984B – NOVEMBER 2009 – REVISED SEPTEMBER 2015

www.ti.com

Changes from Revision A (April 2012) to Revision B

Page

• Added AEC-Q100 test guidance results for temperature grade and HBM and CDM classifications to <i>Features</i> list	1
• Added <i>Pin Configuration and Functions</i> section, <i>ESD Ratings</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section	1
• Replaced references to PowerPAD with thermal pad	1
• Deleted <i>ORDERING INFORMATION</i> table	3
• Deleted <i>DISSIPATION RATINGS TABLE</i>	4
• Changed the thermal metric parameters in the <i>Thermal Information</i> table	4
• Changed the test conditions for REFOUT source and sink current limits in the <i>Electrical Characteristics</i> table	5
• Added -Q1 to device name throughout text of document	23

The datasheet number will be changing.

Device Family	Change From:	Change To:
TPS51200-Q1	SLUS984A	SLUS984B

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/tps51200-q1>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this Notification:

None.

Product Affected:

TPS51200QDRCRQ1

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com